

*Application No. 10/674209*  
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*Amendment*  
*Attorney Docket No. 011.2B-11333-US01*

**Amendments To The Claims:**

1. (Original) A polishing composition used in a polishing process for reducing haze level of wafer surface, comprising:
  - hydroxyethyl cellulose;
  - polyethylene oxide compounded in said composition in a quantity larger than 0.005% by weight and smaller than 0.5% by weight;
  - an alkaline compound;
  - water; and
  - silicon dioxide.
2. (Original) The polishing composition according to claim 1, wherein the total content of iron, nickel, copper, and calcium in the silicon dioxide, as measured in a 20 wt-% aqueous solution of said silicon dioxide, is 300 ppm or less.
3. (Original) The polishing composition according to claim 1, wherein the content of hydroxyethyl cellulose in the polishing composition is 0.1 to 1% by weight.
4. (Original) The polishing composition according to claim 1, wherein the content of silicon dioxide in the polishing composition is 3 to 20% by weight.
5. (Original) The polishing composition according to claim 1, wherein the alkaline compound is ammonia.
6. (Withdrawn)
7. (Withdrawn)
8. (Withdrawn)
9. (Withdrawn)
10. (Withdrawn)
11. (Withdrawn)

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12. (Withdrawn)

13. (Withdrawn)